



Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of “Quality Parts,Customers Priority,Honest Operation,and Considerate Service”,our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



Contact us

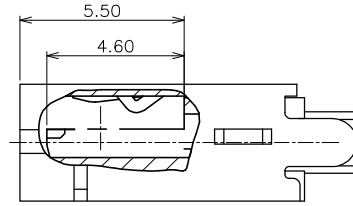
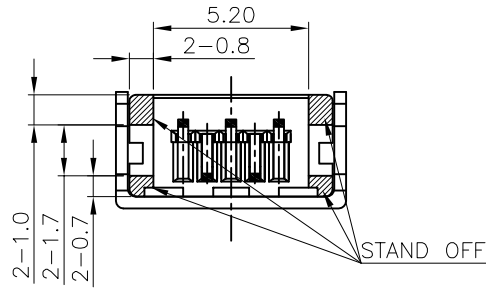
Tel: +86-755-8981 8866 Fax: +86-755-8427 6832

Email & Skype: info@chipsmall.com Web: www.chipsmall.com

Address: A1208, Overseas Decoration Building, #122 Zhenhua RD., Futian, Shenzhen, China



PRODUCT NO.
10119313-*



NOTES:

1.MATERIAL:

HOUSING: THERMOPLASTIC, UL 94V-0 RATED, COLOR IN BLACK.
CONTACT: COPPER ALLOY
SHELL: COPPER ALLOY.

2.FINISH:

CONTACT: UNDERPLATED 50u"MIN. NICKEL, OVER ALL;
100u" MIN. PURE MATTE TIN PLATED IN SOLDERING AREA;
30u" MIN. GOLD PLATING ON CONTACT AREA.
SHIELD: NICKEL 80u" MIN. PLATED OVER ALL.

3. THE HOUSING WILL WITHSTAND EXPOSURE TO 260 DEGREE C PEAK TEMPERATURE FOR 10 SECONDS IN A IR REFLOW APPLICATION, AND THIS PRODCUT MEETS EUROPEAN UNION DIRECTIVES AND OTHER COUNTRY REGULATIONS AS DESCRIBED IN GS-22-008.

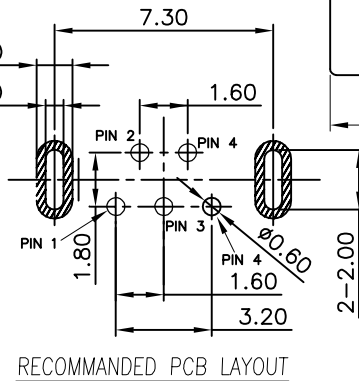
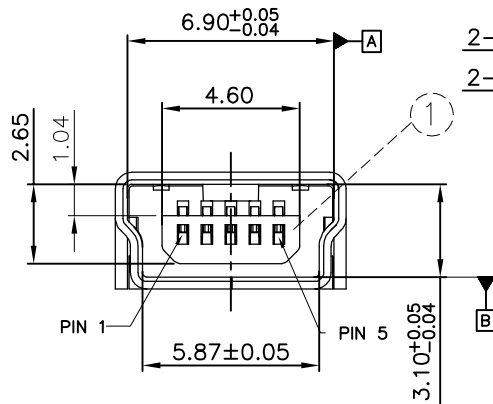
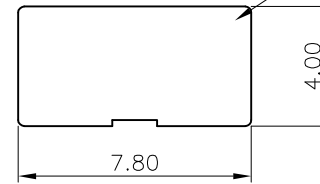
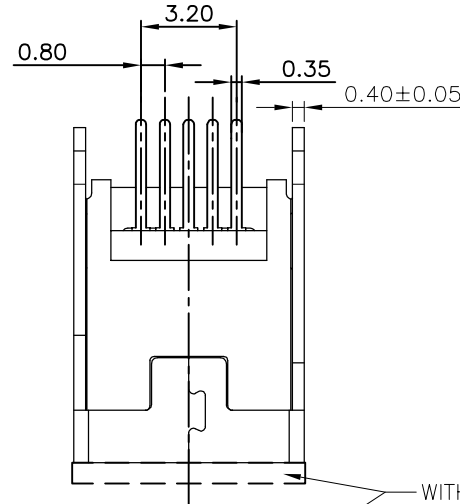
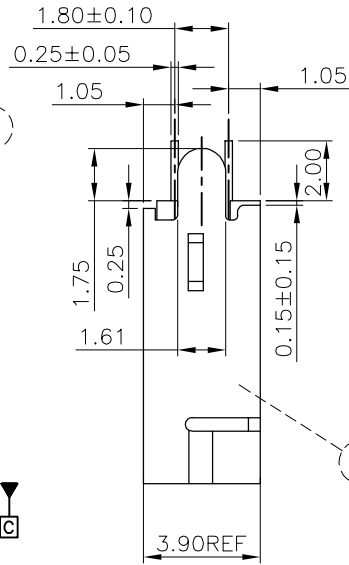
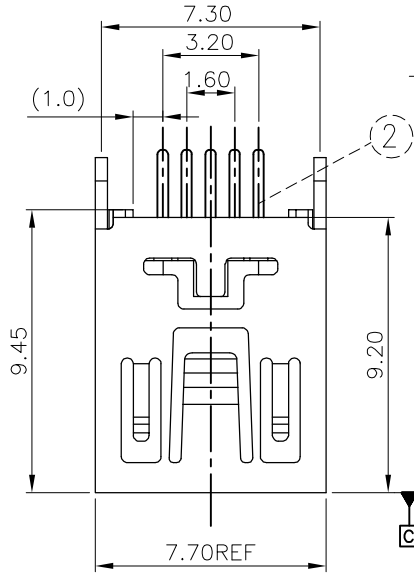
4. PRODUCT SPECIFICATION: GS-12-174; PACKAGING SPECIFICATION: GS-14-873.

5. PRODUCT ORDERING DATA :

FOR LEAD-FREE

10119313 -X X X X LF

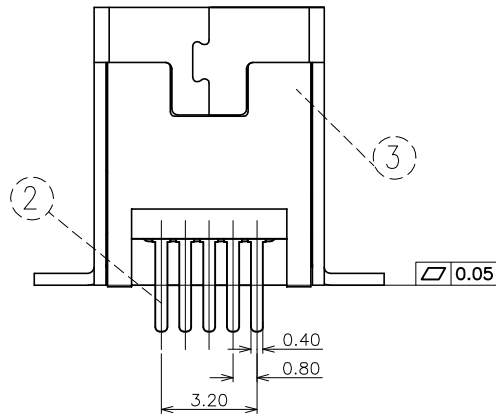
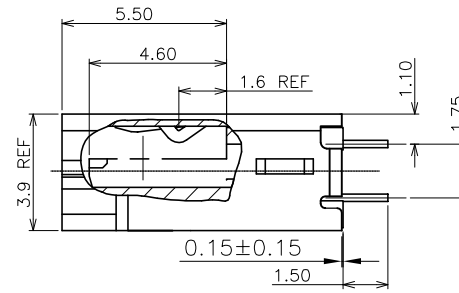
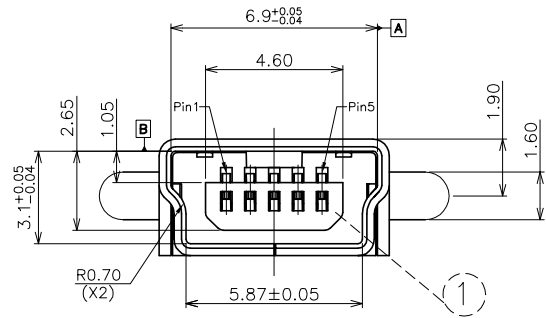
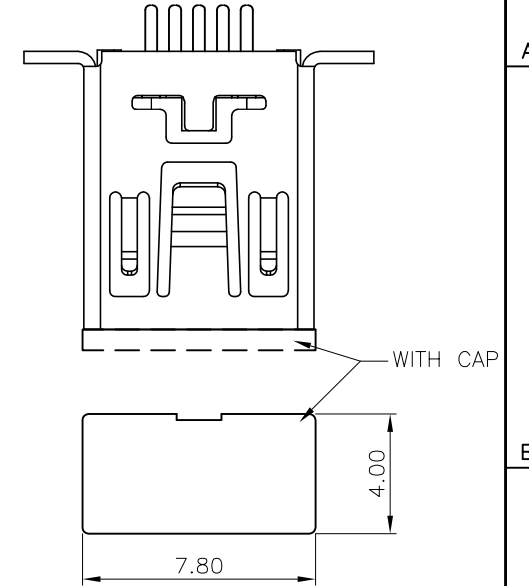
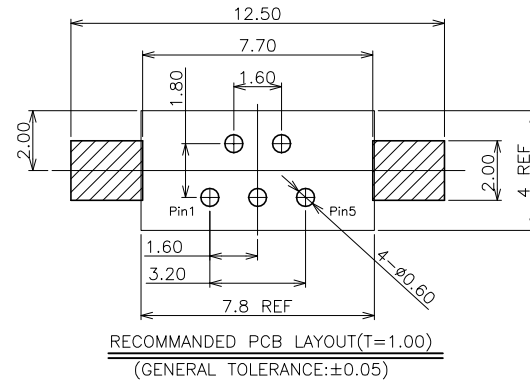
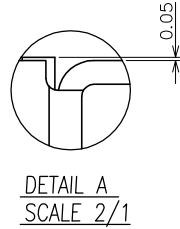
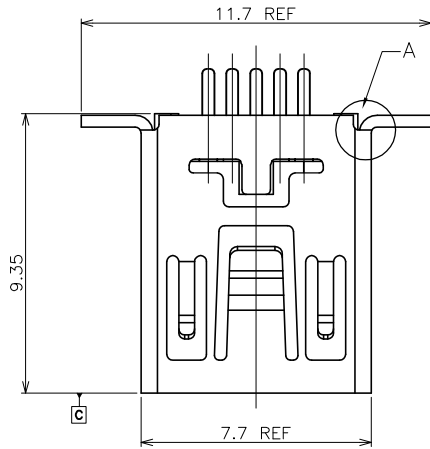
- LF: LEAD FREE PLATING
- PACKAGING METHOD:
- T: TRAY PACKAGING STYLE.
- R: TAPE AND REEL PACKAGING STYLE.
- C: TAPE AND REEL WITH CAP
- SHELL PEG OPTION:
- 1: DIP TYPE, SEE PAGE 1
- 2: SMT TYPE, SEE PAGE 2
- HSG MATERIAL:
- 0: LCP
- PLATING IN CONTACT AREA:
- 3: 30u" MIN. Au .






ITEM	NAMES	QT'Y	MATERIAL	FINISH
3	SHIELD	1	COPPER ALLOY	SEE NOTE 2
2	TERMINAL	5	COPPER ALLOY	SEE NOTE 2
1	HOUSING	1	THERMOPLASTIC	COLOR:BLACK

mat'l. code				tolerances unless otherwise specified		CUSTOMER COPY		FCI	
ltr	ecn no	dr	date	linear	.0 ± 0.30	projection	www.fciconnect.com		
A	-	A.ZH	05/03/12		.00 ± 0.20		title		
B	ELX-N-16102	J.H	10/21/13		.000 ± 0.10		MINI USB 5PF VERTICAL TYPE		
C	ELX-N-17159	L.Q	3/10/14	angles	± 2°		MINI USB B RECEPTACLE		
D	ELX-N-22660	L.Q	12/01/15	dr	ANDY ZHANG	05/03/2012	MM	product family: Mini USB	
				enr	ANDY ZHANG	05/03/2012		code	
				chr	RICK BIAN	05/03/2012	scale	size	
				appd	RICK BIAN	05/03/2012	1 : 1	A4	
sheet index	revision sheet	D	1~2					10119313	
								sheet 1 of 2	
								NT	

PRODUCT NO.
10119313-*



PLEASE SEE PAGE ONE FOR THE NOTES

mat'l. code		tolerances unless otherwise specified		CUSTOMER COPY		 www.fciconnect.com			
ltr	ecn no	dr	date	linear	.0 ± 0.30	projection			
D					.00 ± 0.20				
				angles	.000 ± 0.10				
					± 2°		title MINI USB 5PF VERTICAL TYPE MINI USB B RECEPTACLE		
		dr	ANDY ZHANG	05/03/2012	MM			product family: Mini USB	code NT
		enr	ANDY ZHANG	05/03/2012	← →			size dwg no	sheet 2 of 2
		chr	RICK BIAN	05/03/2012	scale			10119313	
		appd	RICK BIAN	05/03/2012	1 : 1	A4			
sheet index	revision sheet								